

Qualification Results Summary for Assembly Site Transfer and Addition of a Polyimide Passivation Layer to the ADuM7240/ADuM7241 Devices

QUALIFICATION PLAN / STATUS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
High Temperature Operating Life (HTOL)*	JEDEC <i>JESD22-A108</i>	9x77	Pass
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	9x77	Pass
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	9x77	Pass
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	9x77	Pass
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	9x77	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	1x30	Pass
Latch-Up	JEDEC <i>JESD78</i>	1x9	Pass ±100mA @ +5.5V
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JS-001</i>	1x18	Pass ±3000V
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	1x18	Pass ±1250V

*Preconditioned per JEDEC/IPC J-STD-020

Material Set Comparison:

Package Material Set		From: Carsem, Malaysia	To: ASE, Taiwan
SOIC_N	Die Attach Material	Ablestik 84-1LMIS R4	Hitachi EN-4900GC
	Mold Compound	Sumitomo G600	Sumitomo G700LY
	Wire	1.0 mil Gold Wire	1.0 mil Gold Wire